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JUN 29 2006

Patent

Customer No.: 31561  
Docket No. 12476-US-PA  
Application No.: 10/708,488

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of  
Applicant : Kao et al.  
Application No. : 10/708,488  
Filed : March 7, 2004  
For : METHOD OF FORMING BOND MICROSTRUCTURE  
Art Unit : 1725  
Examiner : BEVERIDGE, RACHEL E

**TRANSMITTAL LETTER**

+1-571-273-8300

(Via Fax: 1+6 pages)

Assistant Commissioner for Patents  
Alexandria, VA 22314

Dear Sir,

In response to the Notice of Non-Compliant Amendment dated June 19, 2006 please find the Supplemental Amendment in 6 pages.

The Commissioner is authorized to charge any fees required in connection with the filing of this paper to account No.: 50-2620 (Order No.: 12476-US-PA).

Thank you for your assistance in the subject matter. If you have any questions, please feel free to contact me.

Respectfully Submitted,  
JIANQ CHYUN Intellectual Property Office

Date: June 29, 2006

By: Belinda Lee  
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Group Art Unit: 1725

AMENDMENT

) Attorney Docket: 12476-US-PA

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